1. Chapter 1: Introduction to cybersecurity
   1.1. Why does security matter?
   1.2. Security framework: view of a typical embedded application

2. Chapter 2: Risk assessment and security discovery process
   2.1. Threats or threat modeling (attackers’ capabilities and attack surfaces)
   2.2. Map your security measures to security enablers
   2.3. Security discovery process examples
   2.4. Selecting the appropriate device

3. Chapter 3: How to implement security
   3.1. Terminology
   3.2. Detailed security goals and definitions
   3.3. Elements for building an embedded application with security features

4. Chapter 4: Threats and adversaries
   4.1. Network threats
   4.2. Board threats
   4.3. Chip threats
   4.4. Some examples of consequences of poor security
   4.5. Leveraging industry standards and specifications for security

5. Chapter 5: TI and security
   5.1. A long history

6. Chapter 6: Overview of TI solutions to help implement security measures
   6.1. SimpleLink™ Bluetooth® low energy
   6.2. SimpleLink Sub-1 GHz
   6.3. SimpleLink Wi-Fi®
   6.4. C2000
   6.5. SimpleLink MSP432™ MCUs
   6.6. MSP430™ MCUs
   6.7. Processors
   6.8. Auto processors

7. Conclusion

8. Appendix
   8.1. Resources
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